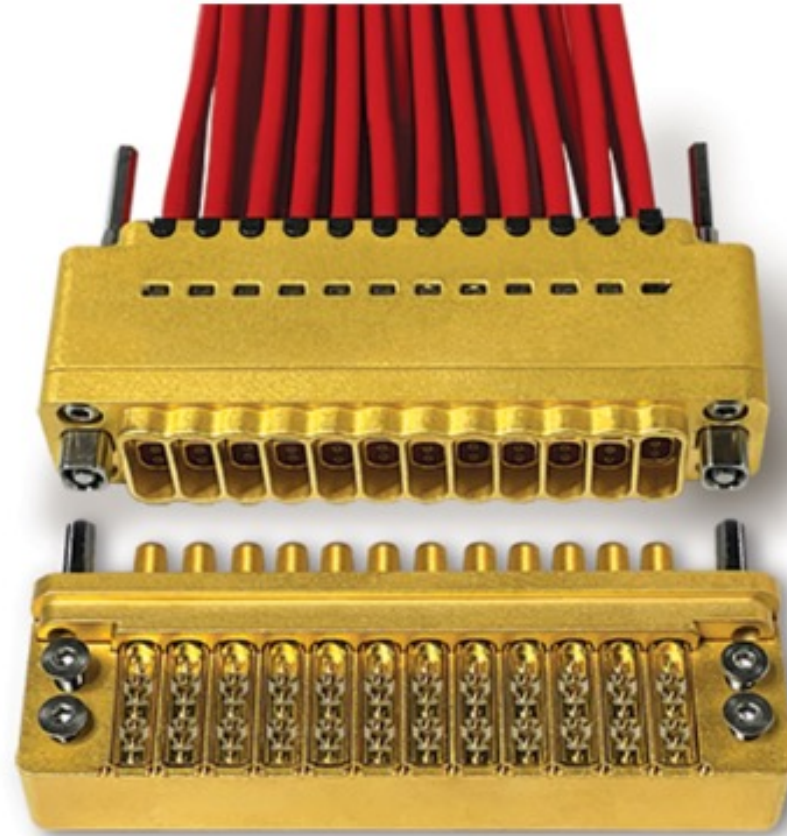




NXS Series Interconnect System – Technical Attributes
Dan Neary, Greg Kay, John Anderson, Steven Douglas Robert Friedt
10/18/22

BEYOND
CONNECTIVITY

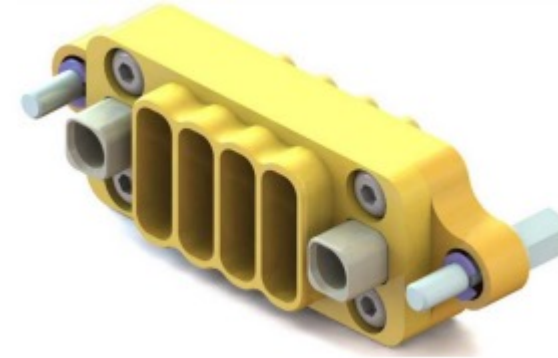
NXS Series Interconnect System



- **Space Qualified**
- **High Data transmission**
- **Solderless**
- **High Density**
- **Light weight**
- **Modular**

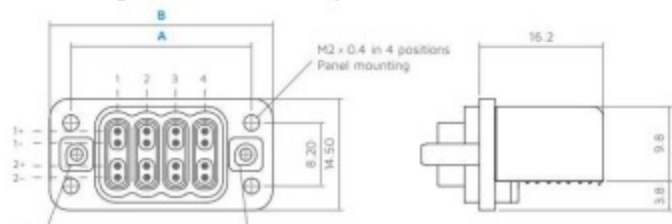
■ Configuration

- 4 and 12 Bay
- Cable to PCB or Flexi-rigid interconnect
- Daughter Card to Backplane
- Module to Module arrangements
- Savers can be used to facilitate test and integration activities



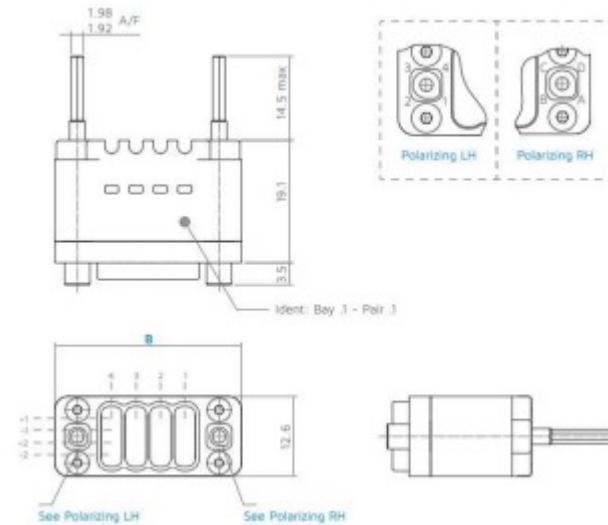
NXS Series Interconnect System

- **Compact Dimensions**
- **Compatible with Shielded Twinax, PCB Layout and Isolation between Modules**



Number of ways	A	B
4	23.6	29.1
12	54.0	59.5

Dimensions are in mm.

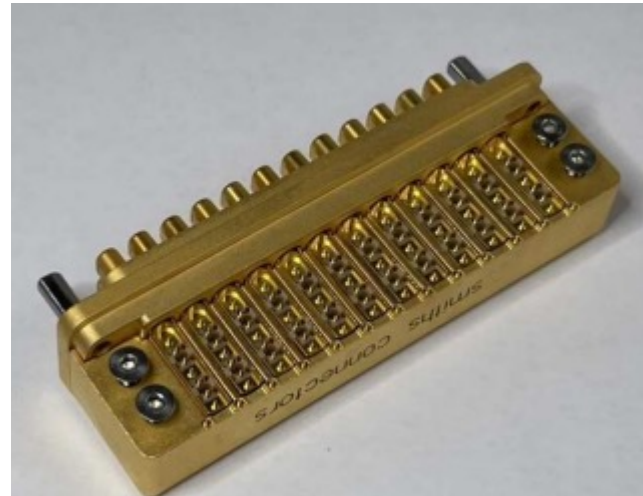


- **Performance Summary**

Parameter	Level
Working Voltage	50 V RMS
Current	1 A
Data Transmission Rate	Up to 50 Gbps per channel
Impedance	100 Ω +/- 10%
Contact resistance	150 m Ω max
Insulation Resistance	1 G Ω min
Operating Temperature	-40°C to +125°C
Durability (saver fitted)	500 cycles

NXS Series Interconnect System

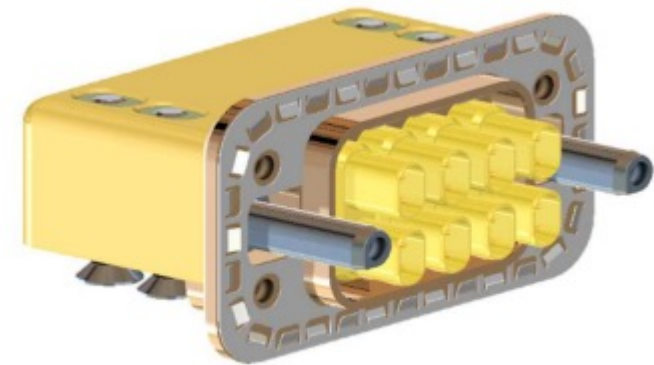
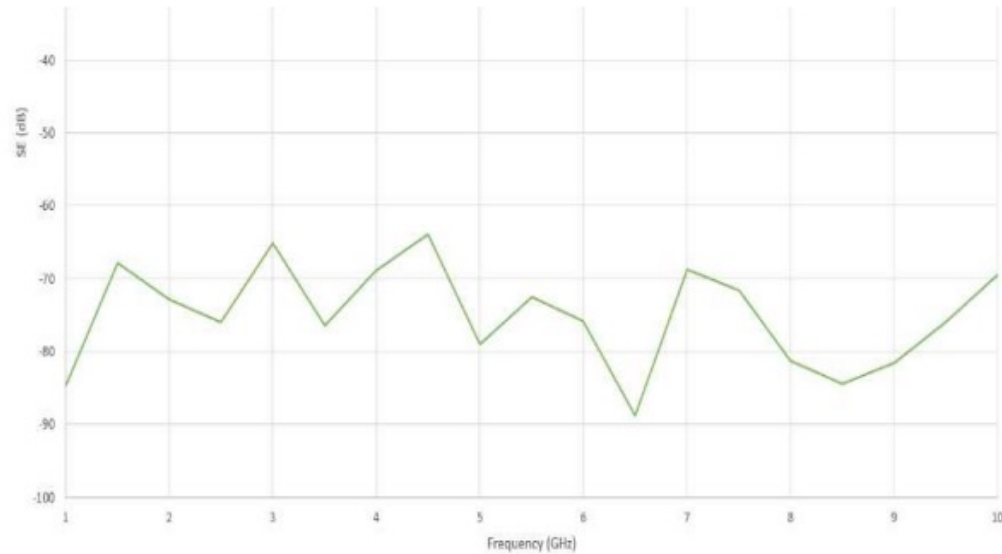
- **Mass**
 - Carbon reinforced PEEK composite polymer with gold over nickel
- **Modularity**
 - 4 and 12 bay
 - 1 or 2 twinax differential pairs as required
- **Hyperboloid Contact Technology**
 - NXS interface contact Micro-boloid
 - Male pin 0.4mm
- **Solderless Terminations**
 - Spring probe technology
 - Prevents typical quality concerns



NXS Series Interconnect System

EMI Performance

- fully shielded from end to end
- a specifically designed EMI gasket combined with a metallic connector housing provides robust and reliable 360 degree shielding
- exceeds 65dB attenuation at 10 GHz





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